Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Is Now Part of

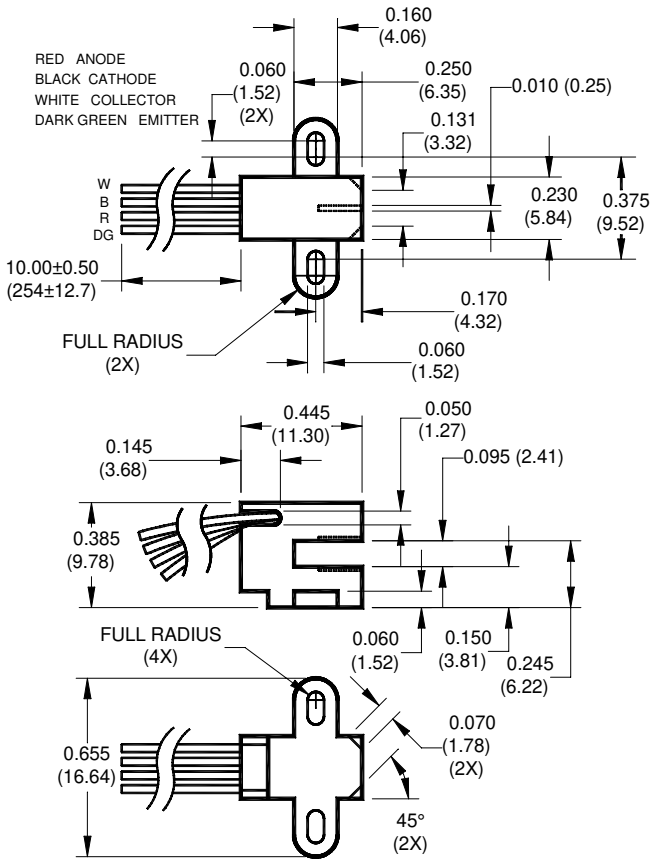
ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at
www.onsemi.com

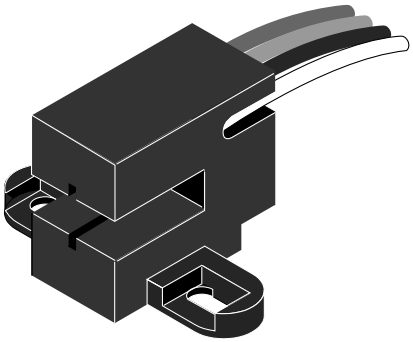
FAIRCHILD
SEMICONDUCTOR™

QVE00039
PHOTOTRANSISTOR OPTICAL INTERRUPTER SWITCH

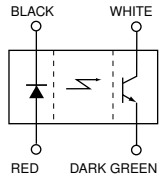
PACKAGE DIMENSIONS



NOTES:
1. Dimensions are in inches (mm)
2. Tolerance of ± .010 (.25) on all non nominal dimensions unless otherwise specified.
3. Wire gauge: 28 AWG



SCHEMATIC



FEATURES

- No contact switching
- 2.41 mm wide slot
- Slot horizontal to mounting surface
- Mounting tabs
- Transistor Output
- Wire leads for remote connection 10” (254mm)
- Opaque black plastic housing
- 0.010 (0.25) aperture width

NOTES (Applies to Max Ratings and Characteristics Tables.)

1. Derate power dissipation linearly 1.67 mW/°C above 25°C.
2. RMA flux is recommended.
3. Methanol or isopropyl alcohols are recommended as cleaning agents.
4. Soldering iron 1/16” (1.6mm) minimum from housing.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Rating	Units
Operating Temperature	T_{OPR}	-40 to +85	°C
Storage Temperature	T_{STG}	-40 to +85	°C
Lead Soldering Temperature (Iron)(2,3,4)	T_{SOL-I}	240 for 5 sec	°C
EMITTER			
Continuous Forward Current	I_F	50	mA
Reverse Voltage	V_R	5	V
Power Dissipation(1)	P_D	100	mW
SENSOR			
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Collector Voltage	V_{ECO}	4.5	V
Power Dissipation(1)	P_D	100	mW

ELECTRICAL / OPTICAL CHARACTERISTICS (T_A = 25°C)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
EMITTER						
Forward Voltage	I_F = 20 mA	V_F	—	—	1.7	V
Reverse Current	V_R = 5 V	I_R	—	—	100	μA
Peak Emission Wavelength	I_F = 20 mA	λ_{PE}	—	940	—	nm
SENSOR						
Collector-Emitter Breakdown	I_C = 1 mA	BV_{CEO}	30	—	—	V
Emitter-Collector Breakdown	I_E = 0.1 mA	BV_{ECO}	5	—	—	V
Dark Current	V_{CE} = 10 V, I_F = 0 mA	I_D	—	—	100	nA
COUPLED						
Collector Current	I_F = 20 mA, V_{CE} = 10 V	$I_{C(ON)}$	0.5	—	—	mA
Collector Emitter Saturation Voltage	I_F = 20 mA, I_C = 0.4 mA	$V_{CE\ (SAT)}$	—	—	0.4	V
Rise Time	V_{CE} = 5 V, R_L = 100 Ω	t_r	—	8	—	μs
Fall Time	$I_{C(ON)}$ = 5 mA	t_f	—	50	—	μs

TYPICAL PERFORMANCE CURVES

Fig. 1 Forward Voltage vs. Ambient Temperature

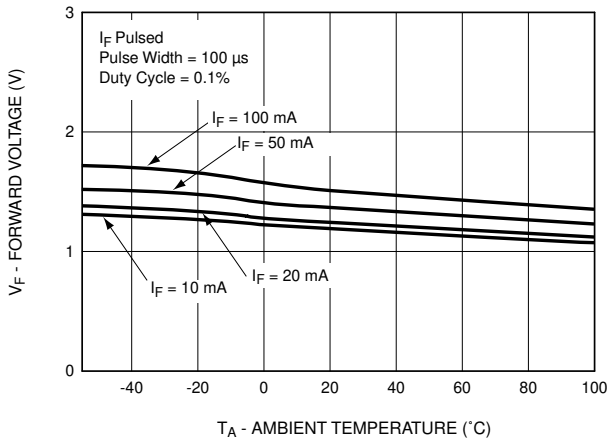


Fig. 2 Forward Current Vs. Forward Voltage

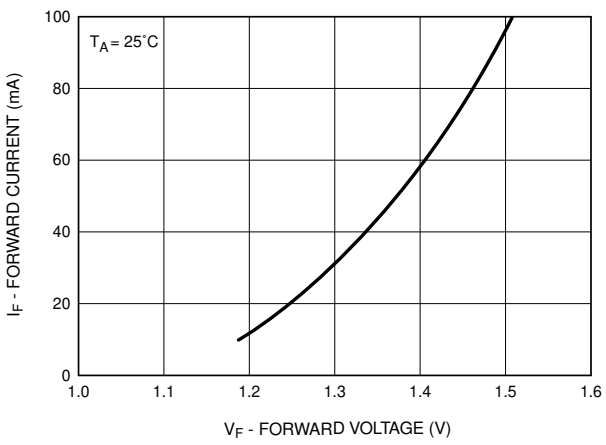


Fig. 3 Collector Emitter Dark Current (Normalized) vs. Ambient Temperature

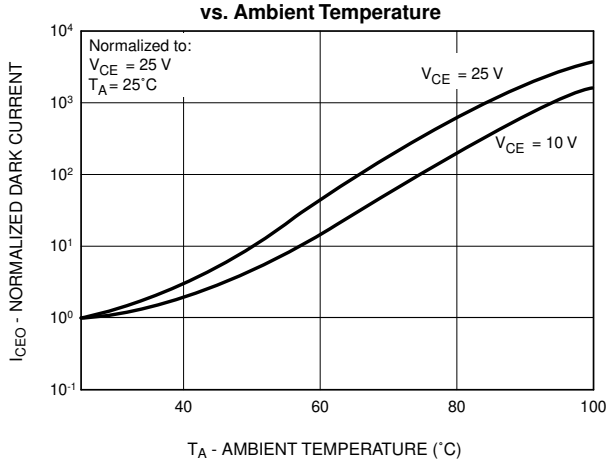


Fig. 4 Rise and Fall Time vs. Load Resistance

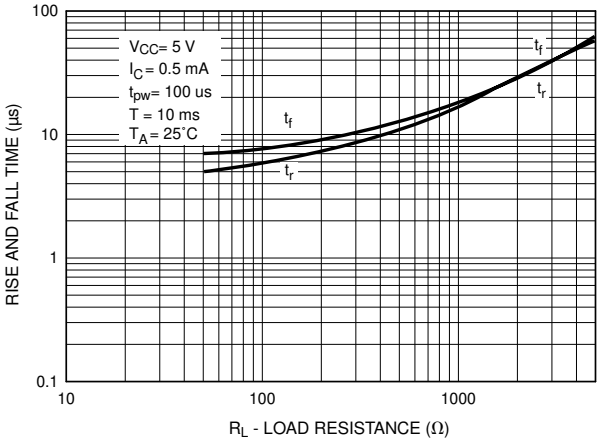


Fig. 5 Normalized Collector Current vs. Forward Current

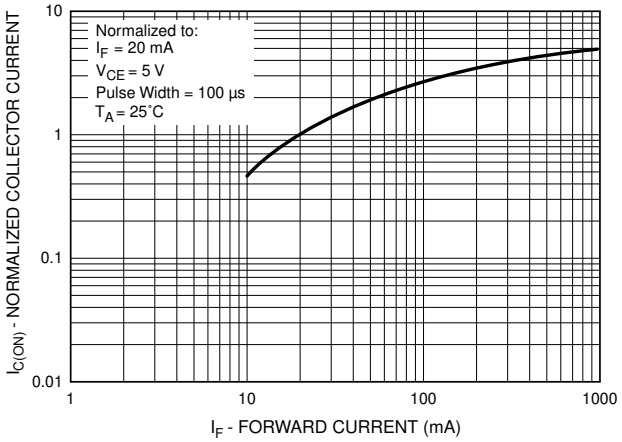


Fig. 6 Collector Current vs. Collector to Emitter Voltage

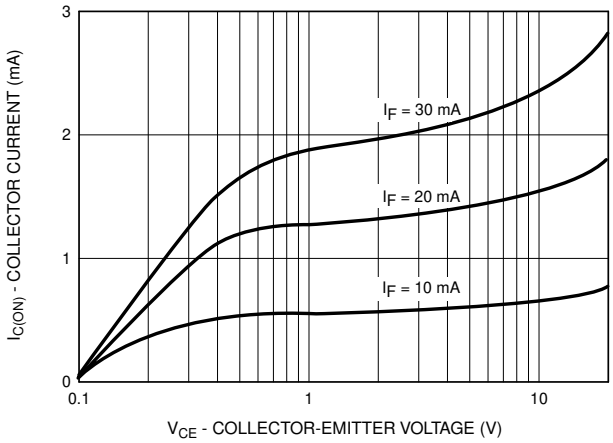


Fig. 7 Normalized Collector Current vs. Ambient Temperature

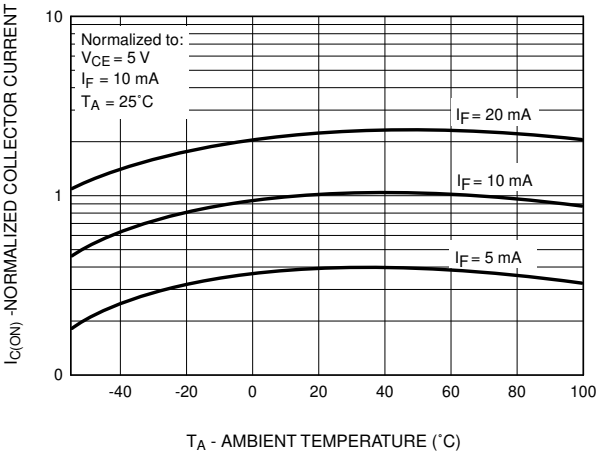


Fig. 8 Normalized Collector Current vs. Shield Distance

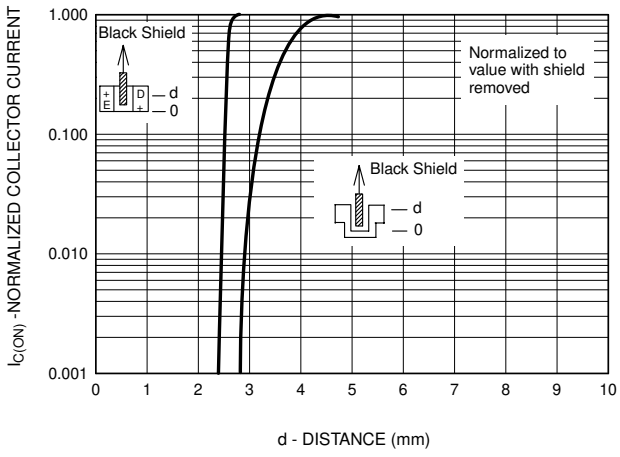
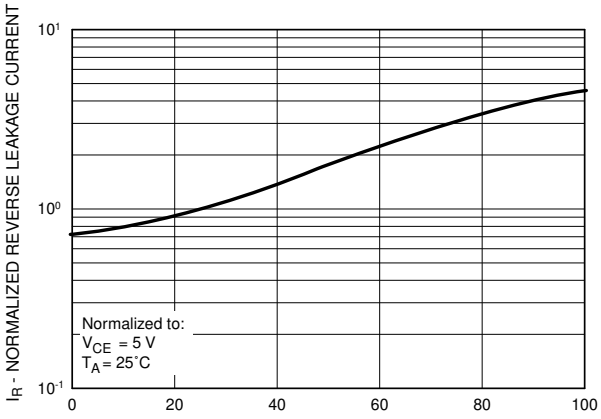


Fig. 9 Normalized Reverse Leakage Current vs. Ambient Temperature



DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative